



# A NEW DAY FOR THE DATACENTER

**FORREST NORROD**

SVP AND GENERAL MANAGER,  
ENTERPRISE, EMBEDDED AND SEMI CUSTOM BUSINESS GROUP

## CAUTIONARY STATEMENT

This presentation contains forward-looking statements concerning Advanced Micro Devices, Inc. (AMD) including, but not limited to: AMD's strategy, focus, vision, forecast, future plans, growth opportunities, priorities and expectations; the timing, features, functionality, availability, expectations and benefits of AMD future products; AMD's 2017 commitments including AMD's ability to launch new products, expand margin, grow revenue and drive profitability; AMD's planned future investments and focus, including markets, technology and key decisions; TAM, growth opportunities and the timing of those growth opportunities in PCs, immersive platform, and datacenter markets as well as AMD's ability to grow, increase revenue and gain market share in those markets; AMD's commitment and long term investment in the datacenter market; AMD's ability to disrupt and lead in the datacenter market; AMD's product, technology and financial roadmaps; share and revenue growth opportunities and the timing of those growth opportunities in AMD's Enterprise, Embedded and Semi-custom and Computing and Graphics businesses; AMD's ability to achieve SAM expansion and margin expansion in the Computing and Graphics business; Computing and Graphics' client compute opportunities; AMD's 2020 growth opportunity; AMD's ability to expand non-GAAP gross margin in 2018 and 2020; AMD's 2017 financial priorities and outlook; AMD's 2017 and long-term financial model including revenue, non-GAAP gross margin, non-GAAP operating expense, non-GAAP net income, capital expenditures and non-GAAP earnings per share; AMD's ability to deliver long-term shareholder value; AMD's ability to achieve its long term financial priorities, including revenue growth, gross margin expansion, consistent profitability and a strong balance sheet; AMD's ability to achieve double digit percentage revenue growth; AMD's ability to achieve gross margin expansion through higher ASPs and richer product mix; long-term gross margin drivers; ability of AMD's new products to drive revenue and gross margin expansion; AMD's long-term capital structure and liquidity; and AMD's 2018 and long-term financial model regarding growth and profitability, which are made pursuant to the Safe Harbor provisions of the Private Securities Litigation Reform Act of 1995. Forward-looking statements are commonly identified by words such as "would," "may," "expects," "believes," "plans," "intends," "projects" and other terms with similar meaning. Investors are cautioned that the forward-looking statements in this presentation are based on current beliefs, assumptions and expectations, speak only as of the date of this presentation and involve risks and uncertainties that could cause actual results to differ materially from current expectations. Such statements are subject to certain known and unknown risks and uncertainties, many of which are difficult to predict and generally beyond AMD's control, that could cause actual results and other future events to differ materially from those expressed in, or implied or projected by, the forward-looking information and statements. Investors are urged to review in detail the risks and uncertainties in AMD's Securities and Exchange Commission filings, including but not limited to AMD's Quarterly Report on Form 10-Q for the quarter ended April 1, 2017.

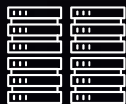
## NON-GAAP FINANCIAL MEASURES

In this presentation, AMD has provided non-GAAP financial measures including non-GAAP gross margin, non-GAAP operating expenses, non-GAAP operating loss, non-GAAP interest expense, non-GAAP net loss, non-GAAP loss per share and Adjusted EBITDA. The non-GAAP financial measures disclosed in this presentation should be viewed in addition to, and not as a substitute for or superior to, AMD's reported results prepared in accordance with GAAP and should be read only in conjunction with AMD's Consolidated Financial Statements prepared in accordance with GAAP. These non-GAAP financial measures referenced are reconciled to their most directly comparable GAAP financial measures in the Appendices at the end of this presentation.



# EESC

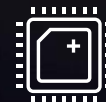
HIGH-PERFORMANCE COMPUTING AND GRAPHICS SOLUTIONS



Enterprise/Server



Embedded



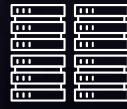
Semi-Custom

# EESC FUNDAMENTALS

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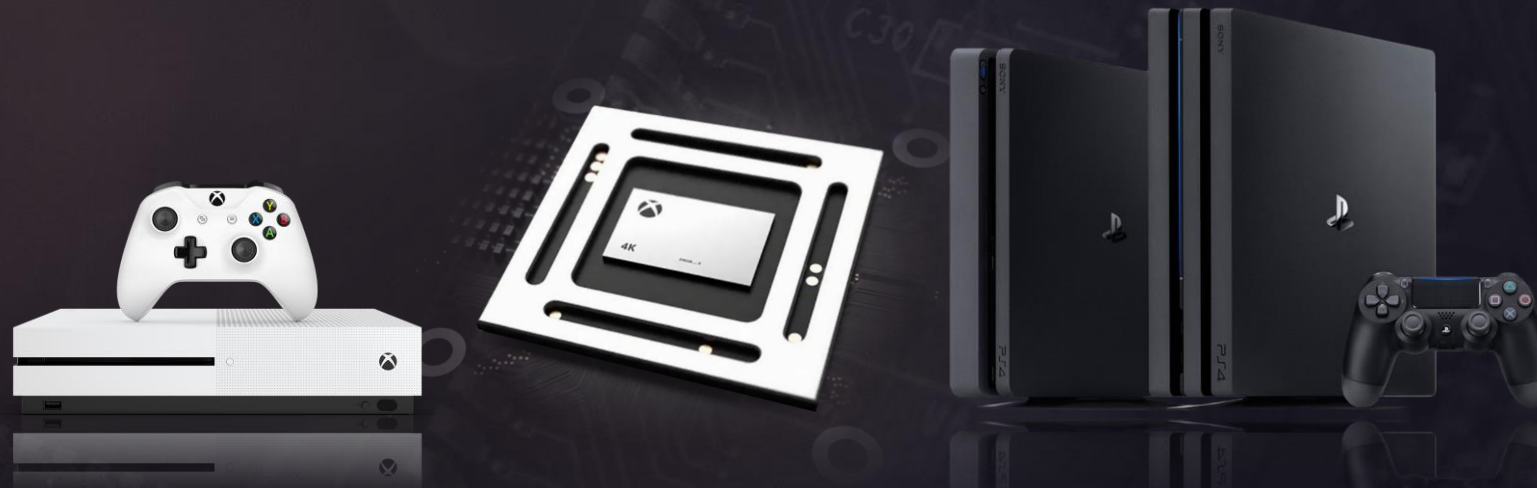
Strong Foundation for  
Future Growth



Differentiated  
Datacenter Products



Expanding Semi-Custom and  
Embedded Opportunities



# SEMI-CUSTOM EXPERTISE

ESTABLISHED GAME CONSOLE LEADERSHIP



PROJECT  
SCORPIO

"It's not a process of calling up AMD and saying I'll take this part, this part and this part. A lot of really specific custom work went into this."

- Kevin Gammill, Microsoft



"How it works is that we sit down with AMD, who are terribly collaborative. It's a real pleasure to work with them."

- Mark Cerny, Sony

# HIGH-PERFORMANCE DIFFERENTIATED SOLUTIONS

High-Performance,  
Scalable Technologies

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Modular SoC and  
Platform Design Capabilities

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Deep Customer Integration  
and Co-Development

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# SEMI-CUSTOM MODEL

# SEMI-CUSTOM & EMBEDDED FOCUS



Gaming



Visual  
Embedded



Imaging



Infrastructure



Datacenter



**#1 PRIORITY**  
DATACENTER  
LEADERSHIP



# AMD FIRST

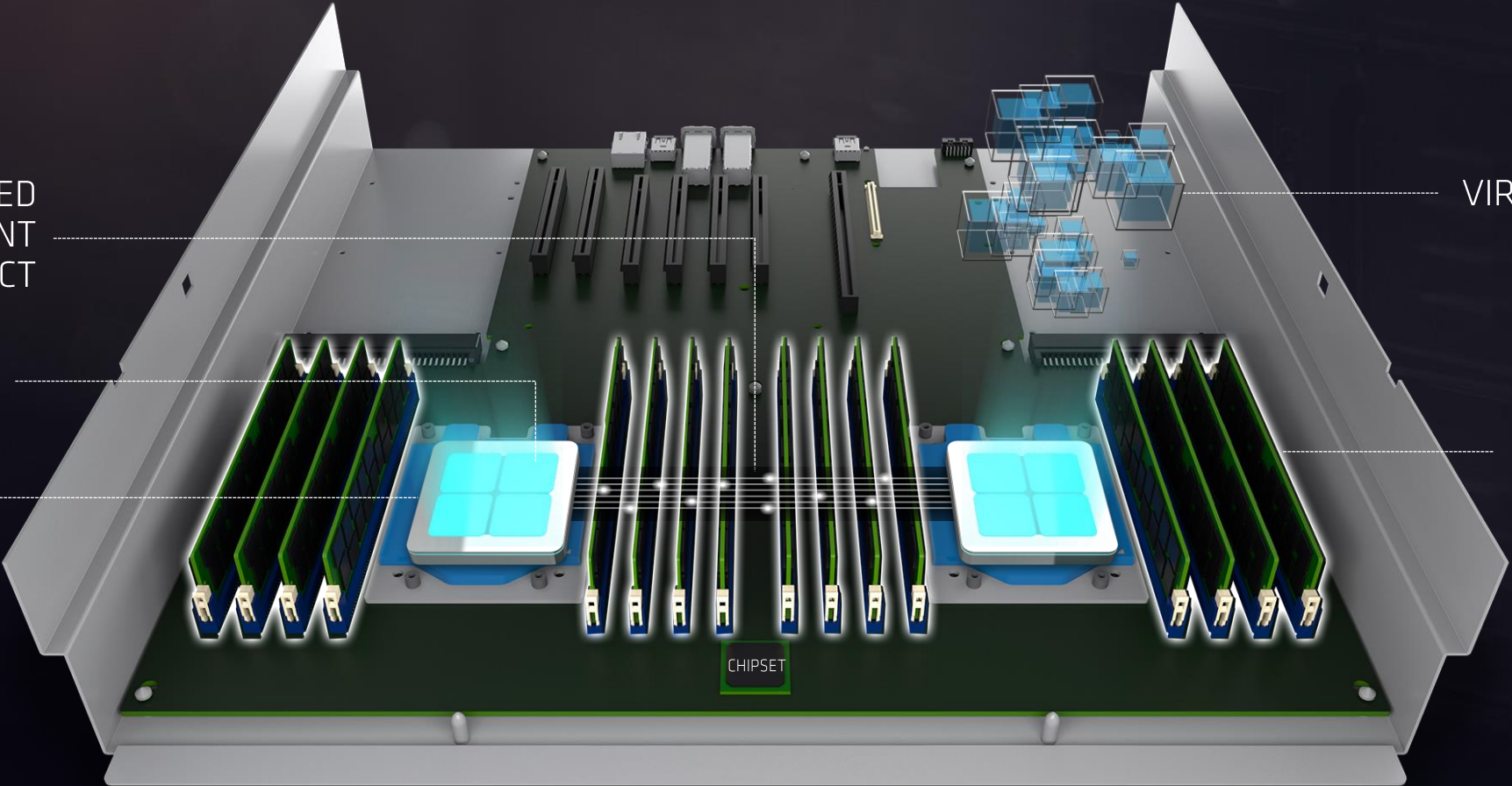
HIGH SPEED  
COHERENT  
INTERCONNECT

VIRTUALIZATION

MULTI-CORE  
PROCESSING

INTEGRATED  
MEMORY  
CONTROLLERS

64-BIT x86





# SERVER MARKET IS STAGNANT

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Performance Limited by  
Unbalanced Designs

“Incrementalism”

Systems Not  
Evolving with Cloud



# PERFORMANCE AND FEATURES FOR **\$16B TAM<sup>1</sup> IN 2020**



Server



Storage



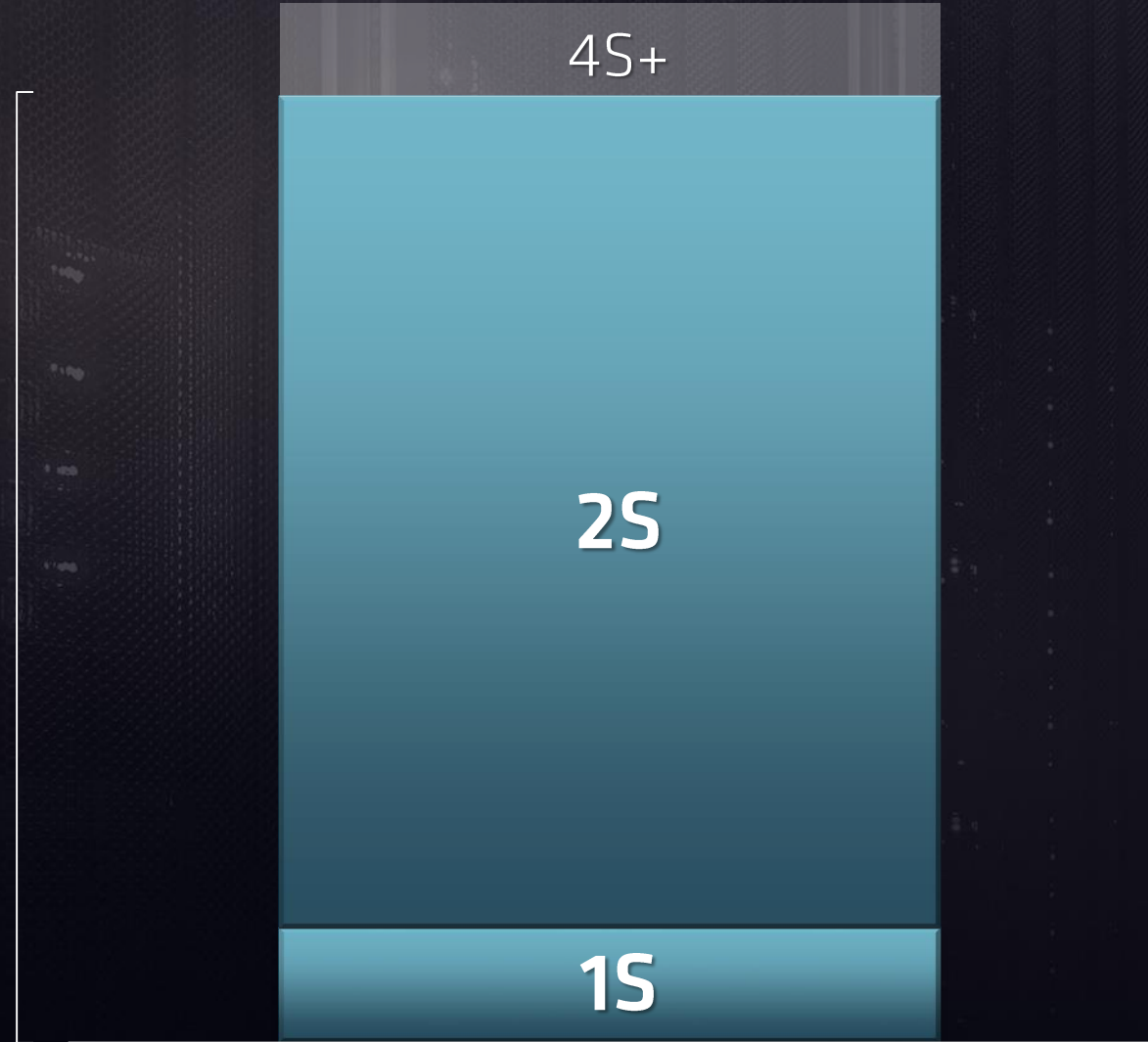
Networking

(1) AMD Internal Estimates for Calendar 2020

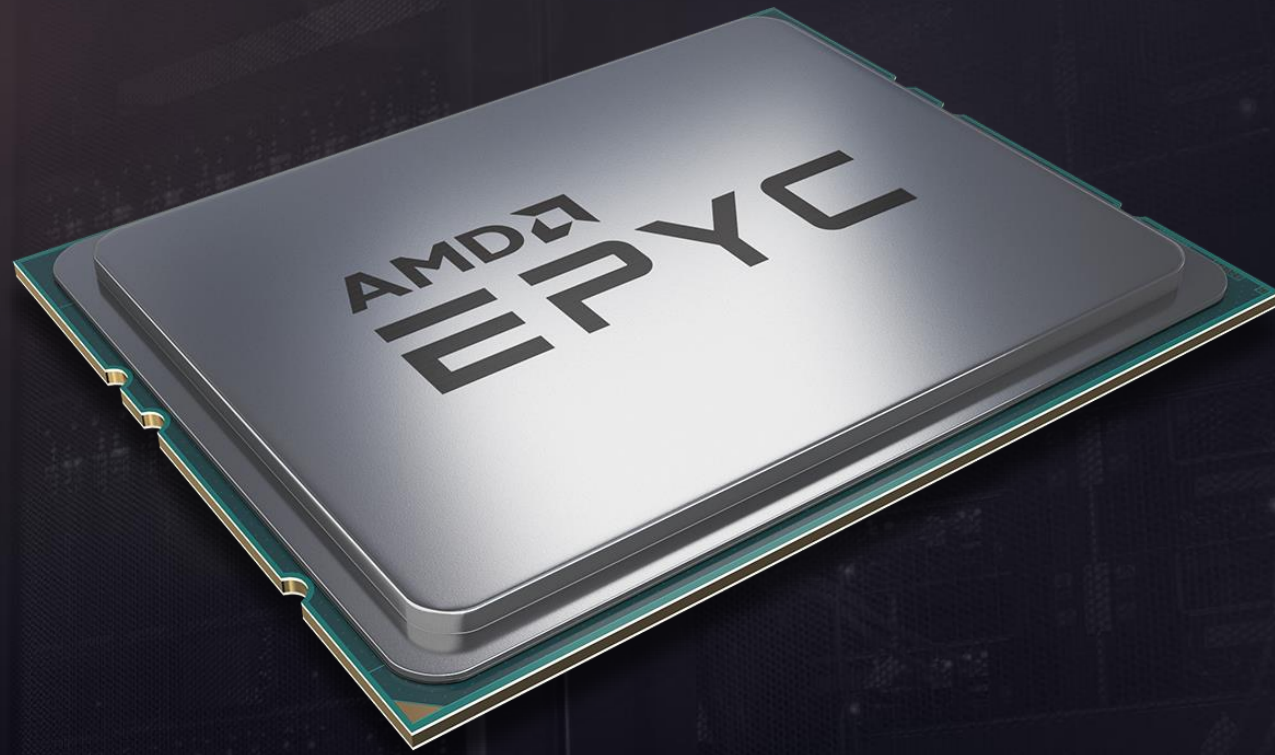


# x86 SERVER MARKET

**91%**  
of the Market  
is Single or  
Dual Socket



2016 Units



32  
"Zen" Cores

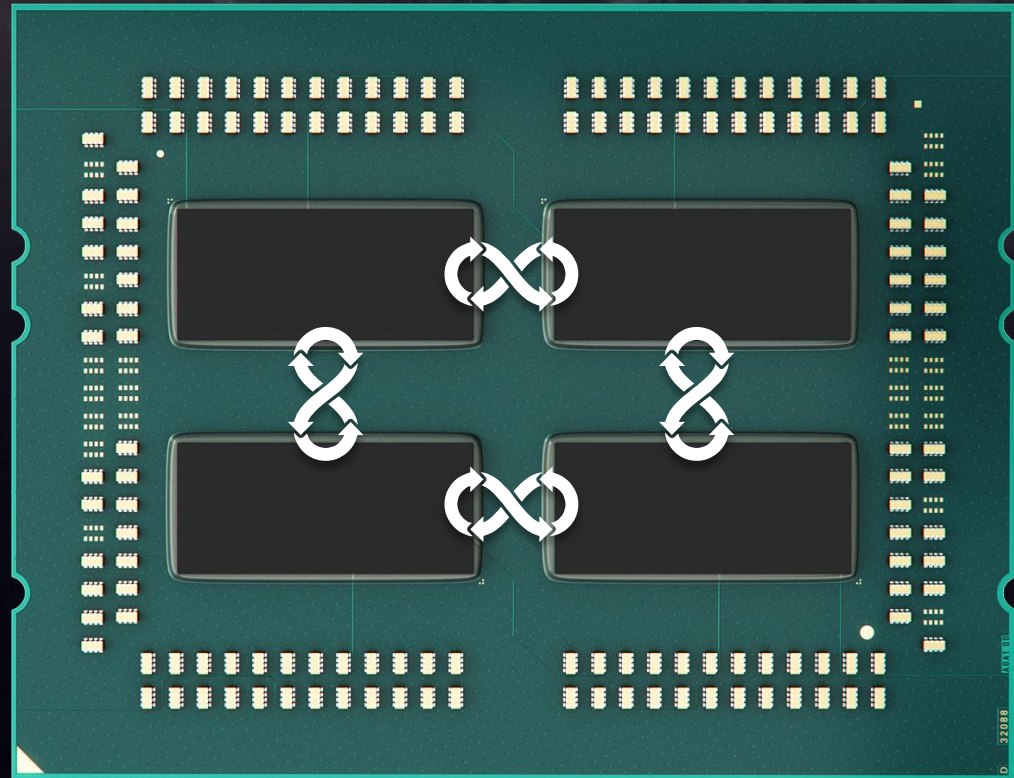
8  
Memory Channels

128 Lanes of  
High-Bandwidth I/O

Dedicated  
Security Engine

# BREAKING CONSTRAINTS OF MOORE'S LAW

- Revolutionary Infinity Fabric
- High-performance, scalable links
- Enables architectural innovations that increase real-world performance
- Improves product yields
- Reduces product costs



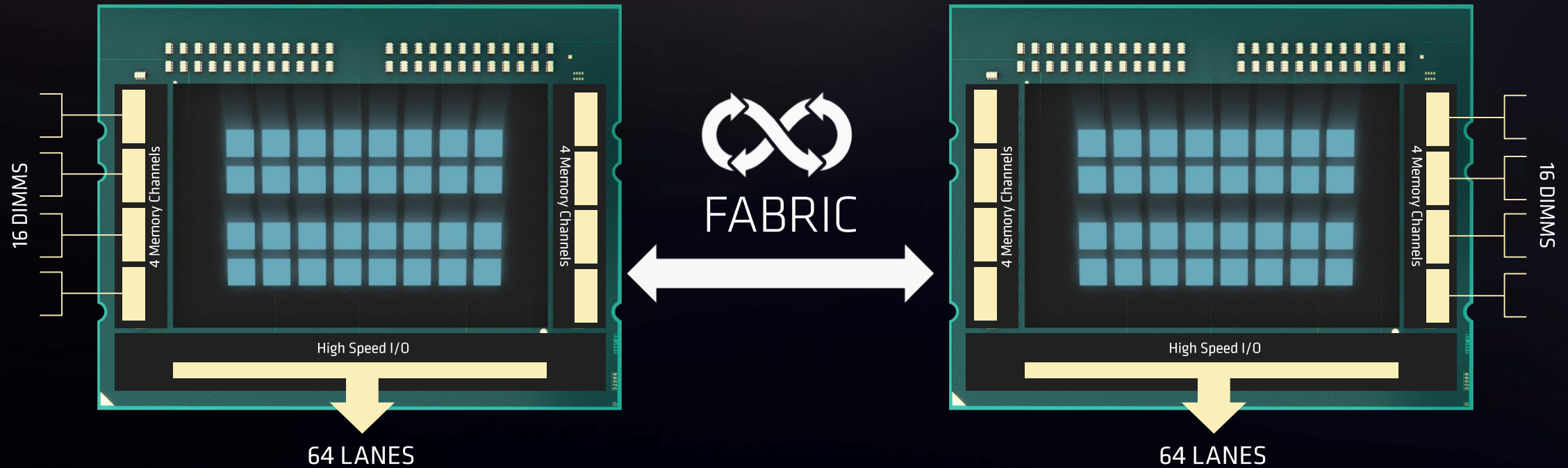


# TWO SOCKET PLATFORM

**64** Cores

**4TB** Memory

**128** PCI Express® Lanes



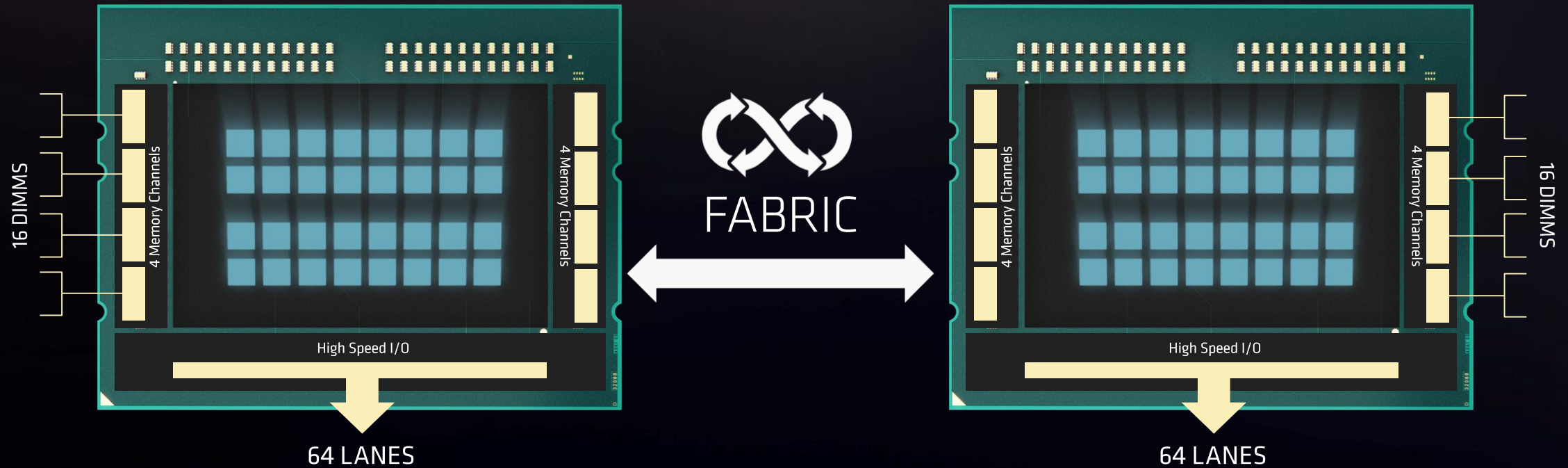


# TWO SOCKET PLATFORM

**45%** More Cores than Competitor

**122%** More Memory Bandwidth than Competitor

**60%** More I/O than Competitor







# LEADERSHIP

High Performance  
Compute



Cloud, Hyperscale,  
and Virtualization



Machine  
Learning



Big Data  
and Analytics



Software-Defined  
Storage





# LEADERSHIP

High Performance  
Compute



Cloud, Hyperscale,  
and Virtualization



Machine  
Learning



Big Data  
and Analytics



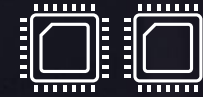
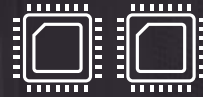
Software-Defined  
Storage



# HIGH-PERFORMANCE VIRTUALIZATION

- Highest-performance dual socket offerings
  - AMD Epyc vs. Intel Xeon® E5 2699A V4
  - VMware hosting Linux® guest VMs
- 8 VMs running compilation of Linux® kernel
  - Compute intensive
  - Performance CPU bound
- Demonstrate compute capability for cloud and enterprise datacenters

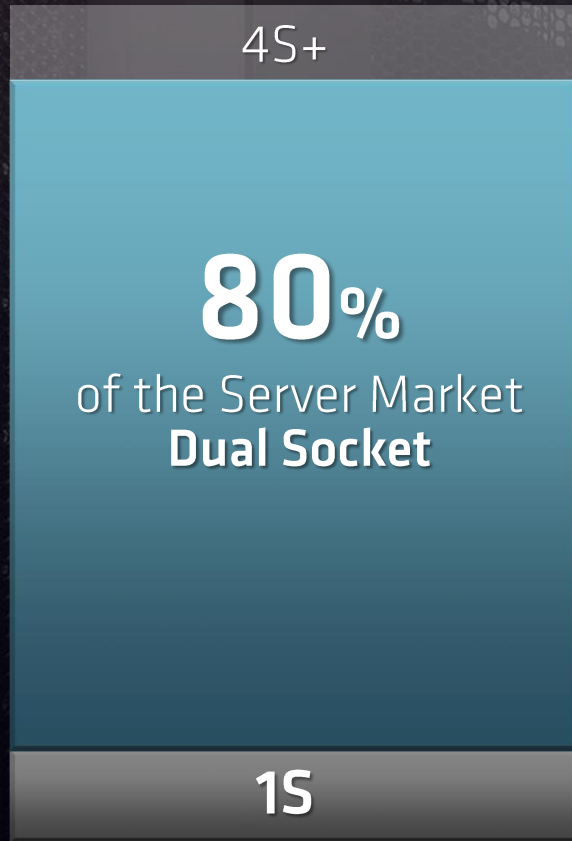
# 2 SOCKET SYSTEM CONFIGURATIONS



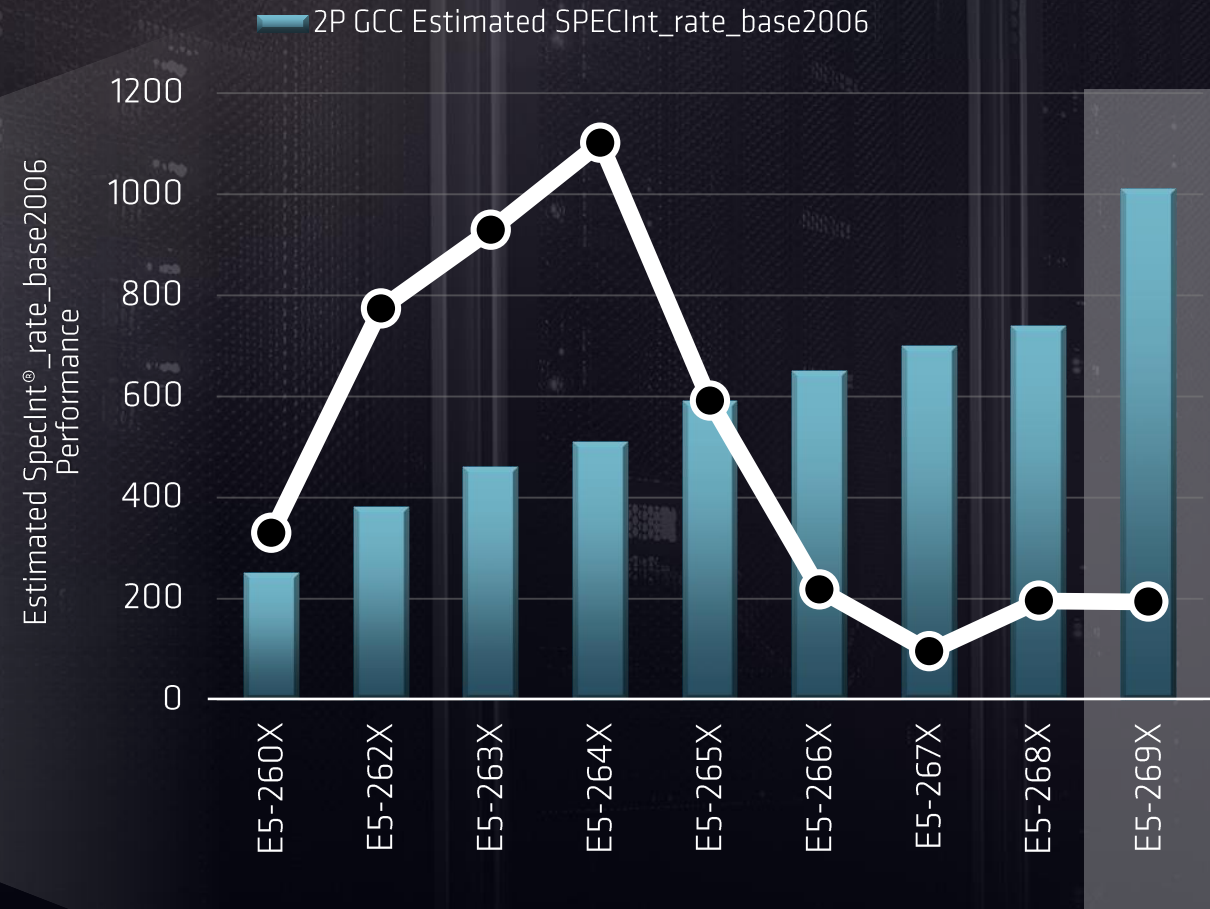
Component	AMD	INTEL
CPU model	<b>EPYC</b>	E5-2699A V4
Sockets	<b>2</b>	2
Total cores	<b>64</b>	44
Total memory channels	<b>16</b>	8
Total populated memory (16 GB DIMMS)	<b>256</b>	128
Memory frequency	<b>2400</b>	2400
Total PCIe® gen3 lanes to CPUs	<b>8x16=128</b>	2x40=80

# x86 SERVER MARKET

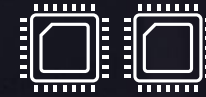
**>50%** of the 2P Shipments are 2650 or Below



2016 Units



# 1S VS. 2S SYSTEM CONFIGURATIONS



Component	AMD	INTEL
CPU model	<b>EPYC</b>	E5-2650 V4
Sockets	<b>1</b>	2
Total cores	<b>32</b>	24
Total memory channels	<b>8</b>	8
Total populated memory (16 GB DIMMS)	<b>128</b>	128
Memory frequency	<b>2400</b>	2400
Total PCIe <sup>®</sup> gen3 lanes to CPUs	<b>8x16=128</b>	2x40=80

48cm x 42cm

Intel

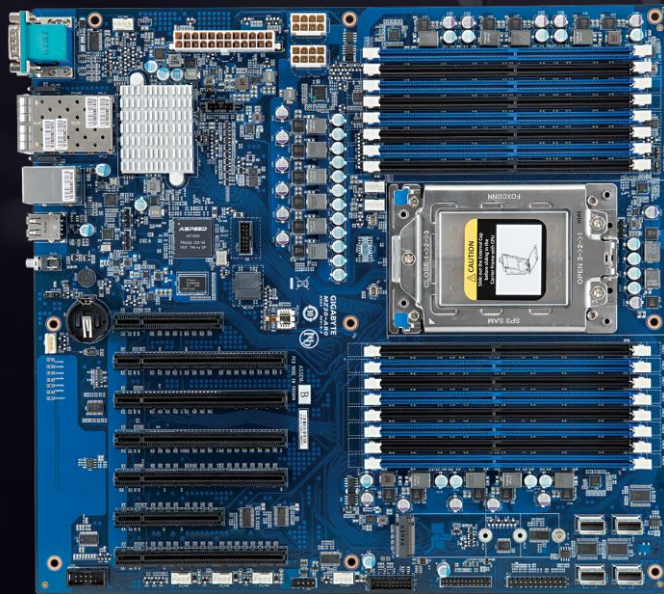
33cm x 30.5cm



**MORE CORES**  
**MORE I/O**  
**GREATER DENSITY**  
**LESS SPACE**  
**LOWER POWER**



# DISRUPTING VOLUME 2S MARKET



- 🏆 **Epyc 1S performance  $\geq$  50% Intel 2S offerings**
- 🏆 **Significantly lower power consumption**
- 📉 **Greatly reduced operating expense**
- 💰 **Up to 30% TCO advantage<sup>1</sup>**

(1) AMD estimate including Speclnt internal measurements. See Endnotes.





## **NO COMPROMISE ONE SOCKET**

Customers Can Match Systems to their  
Workloads Without Compromise

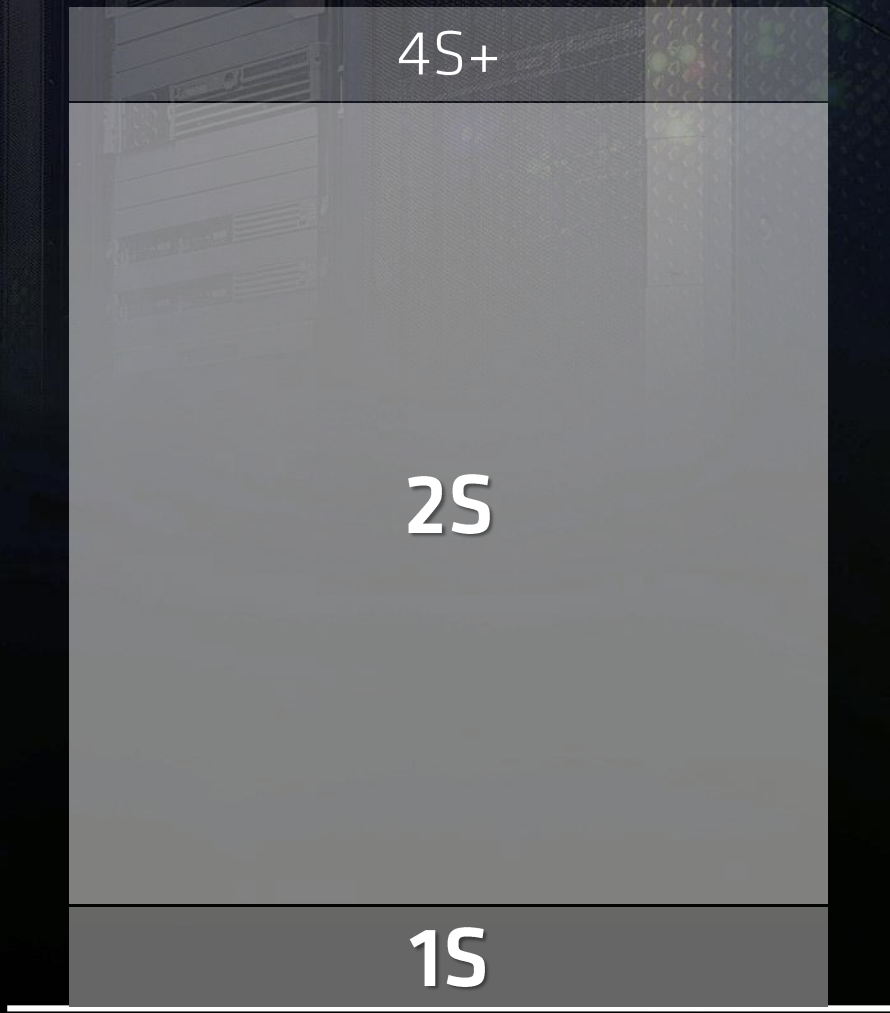
I/O Expansion | Memory Bandwidth | Memory Capacity

## **LEADERSHIP TWO SOCKET**

High-Performance,  
Balanced Architecture

More Cores | More Memory Bandwidth | More I/O

# THE STATUS QUO



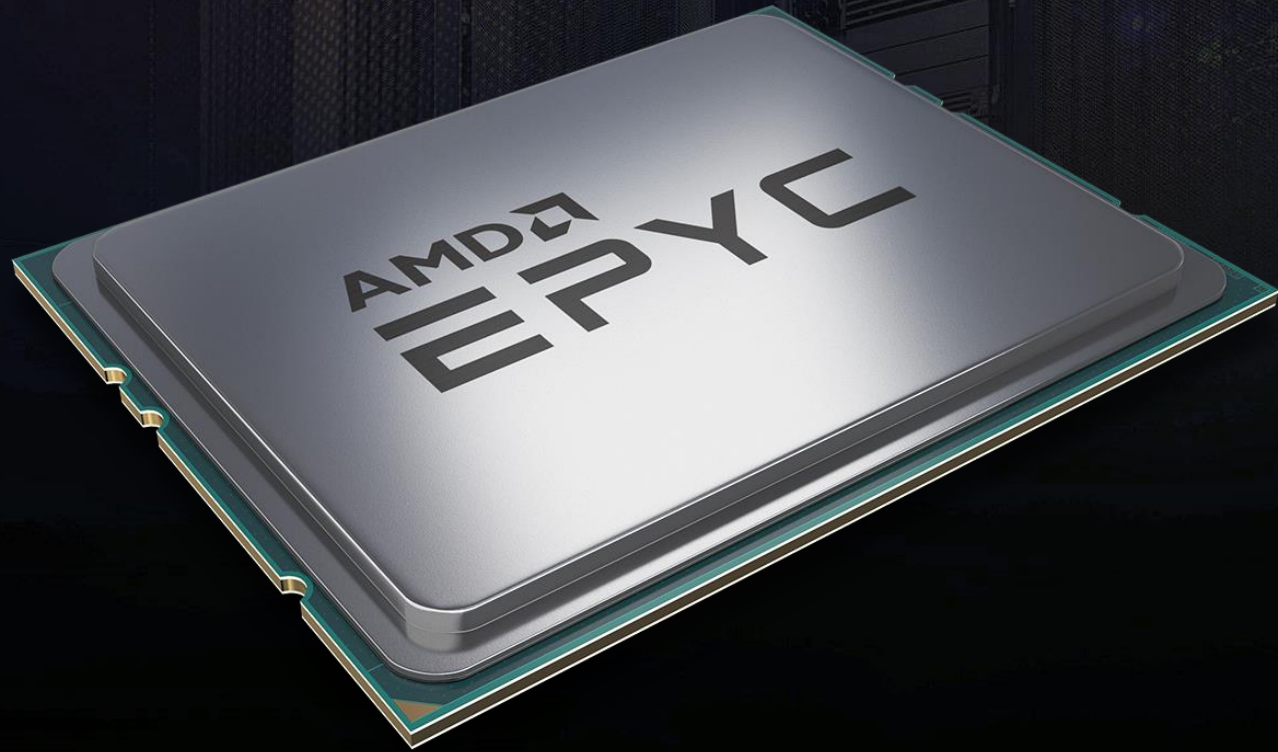
x86 SERVER MARKET

# DISRUPTING THE STATUS QUO



x86 SERVER MARKET

# DISRUPTING THE STATUS QUO



## EVERY EPYC™ PROCESSOR IS UNRESTRAINED

- All I/O
- All reliability features
- All memory channels
- High-speed memory
- Complete security stack
- Integrated chipset



# LEADERSHIP

High Performance  
Compute



Cloud, Hyperscale,  
and Virtualization



Machine  
Learning



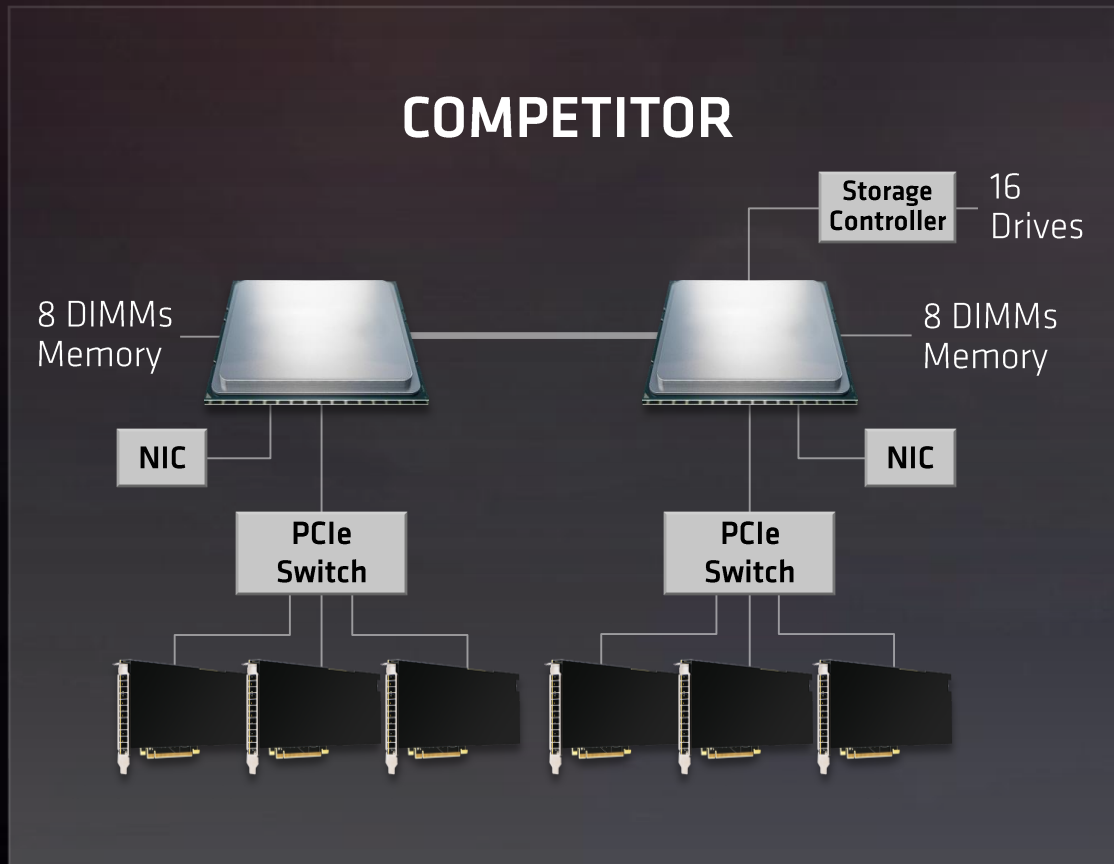
Big Data  
and Analytics



Software-Defined  
Storage

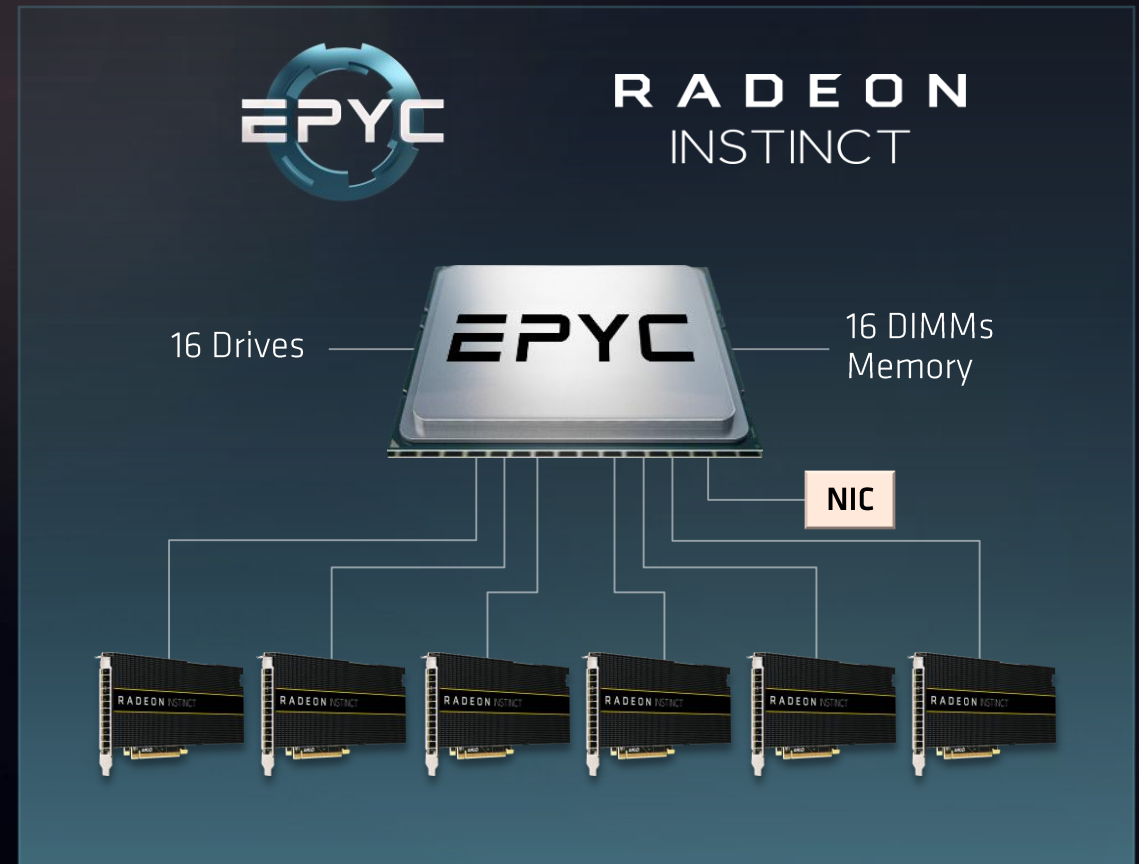


# A SIMPLIFIED MACHINE INTELLIGENCE ARCHITECTURE



Flexible Configurations

Open Ecosystem



Optimized Platforms

Lower TCO



# MARKET MOMENTUM

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**30+**

1S/2S Servers  
Expected in 2017

**5000+**

EPYC™ CPUs Seeded with OEMs,  
End Customers, and Partners



Programs Underway with  
Multiple Hyperscale Providers



June  
Launch

# AMD LONG TERM DATACENTER COMMITMENT



- "Zen"
- 14nm

2017

## "Rome"

- "Zen 2"
- 7nm

## "Milan"

- "Zen 3"
- 7nm+

2020

Continuous Innovation

Performance Leadership





# DATACENTER LEADERSHIP

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Returning Innovation  
to Datacenter Market

Clear Choice for  
Key Workloads

Widespread  
Ecosystem Support

AMD is Back, Investing  
for the Long Term

**AMD** 

# END NOTES

Slide 15/22/24:

- 45% more cores – Epyc 32C versus Intel Xeon E5-2699A v4 processor with 22 Cores (Source: [https://ark.intel.com/products/96899/Intel-Xeon-Processor-E5-2699A-v4-55M-Cache-2\\_40-GHz](https://ark.intel.com/products/96899/Intel-Xeon-Processor-E5-2699A-v4-55M-Cache-2_40-GHz))
- 122% greater memory bandwidth – Epyc Max memory bandwidth of 170.7GB/s. Intel Xeon E5-2699A v4 max memory bandwidth of 76.8GB/s (Source: [https://ark.intel.com/products/96899/Intel-Xeon-Processor-E5-2699A-v4-55M-Cache-2\\_40-GHz](https://ark.intel.com/products/96899/Intel-Xeon-Processor-E5-2699A-v4-55M-Cache-2_40-GHz))
- 60% I/O Density advantage - Epyc maximum of 128 PCI Express lanes. Intel Xeon E5-2699A v4 maximum of 40 PCI Express Lanes per socket, 80 in a two socket configuration (source: [https://ark.intel.com/products/96899/Intel-Xeon-Processor-E5-2699A-v4-55M-Cache-2\\_40-GHz](https://ark.intel.com/products/96899/Intel-Xeon-Processor-E5-2699A-v4-55M-Cache-2_40-GHz) ).

Demo 1: Demonstration conducted by AMD Engineering using a 2P AMD reference system with 32-core Epyc™ processor engineering samples, and an Intel-based 2P OEM production platform, each running the same gcc compile of a bare-bones linux kernel, utilizing a d3 Sunburst Partition visualization (<http://d3js.org>). AMD 2P test platform used 256GB DDR4-2400; Intel Xeon E5-2699A v4 2P test platform used 128GB DDR4-2400. Both platforms ran the same version of VMware vSphere with Ubuntu 17.04 guests, with 8 VMs per server.

Slide 20: x86 Server Market Slide: Estimated 2P GCC SPECint®\_rate\_base2006 scores based off of maximum scores published at <http://www.spec.org> for specified processors. More information about SPEC CPU® 2006 can be found at <http://www.spec.org>

Demo 2: Demonstration conducted by AMD Engineering using an AMD reference system with a 32-core Epyc™ processor pre-production prototype, and an Intel-based OEM production platform, each running the same gcc compile of a bare-bones Linux kernel, utilizing a d3 Sunburst Partition visualization (<http://d3js.org>). AMD 1P test platform used 128GB DDR4-2400; Intel Xeon E5-2650 v4 2P test platform used 128GB DDR4-2400. Both platforms ran the same version of VMware vSphere with Ubuntu 17.04 guests, with 8 VMs per server.

Slide 23: Boards used include Intel HPE DL-380 Gen 9 and Epyc-based re-production Gigabyte 1S server

Slide 23: 32-core Epyc TDP is 180 watts, compared to 2 x Intel 12-core E-2650 v4 TDP at 105 watts each; AMD internal estimate as of May 2017 based on the expected cost for 28 1-socket 32-core Epyc based servers compared to 21 2-socket Intel 12-core (24 total cores) E-2650 v4 based servers, assuming a 3-year useful life, 100% utilization, and electricity cost of \$0.16/Kw hr. Assumes SPECint® score estimates of 697 for Epyc processor and 293 for a single E2650v4 processor scaled at 1.95x for 2 sockets. Additional information about SpecCPU®2006 can be found at [www.spec.org](http://www.spec.org). Estimate is based on AMD internal lab measurements/modelling and may vary.

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